

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

HIROYUKI YANO ET AL

: GROUP ART UNIT: 1765

: EXAMINER: DEO, D.

SERIAL NO. 09/531,163

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RECEIVED

OCT 1 0 2001

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FILED: MARCH 17, 2000

FOR: AQUEOUS DISPERSION, AQUEOUS

DISPERSION FOR CHEMICAL MECHANICAL POLISHING USED FOR MANUFACTURE OF SEMI-CONDUCTOR DEVICES, METHOD

FOR MANUFACTURE OF ...

AMENDMENT AND REQUEST FOR RECONSIDERATION

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Responsive to the Office Action of July 5, 2001, Applicants respectfully request reconsideration of the above-identified application in view of the following amendments and remarks.

IN THE CLAIMS

Please cancel Claims 1-39.

Please add new Claims 44-75 as follows:

44. (New) An aqueous dispersion for chemical mechanical polishing used in the manufacture of semiconductor devices, said dispersion comprising polymer particles, inorganic particles and water, wherein the zeta potential of said polymer particles and the

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